

# SN74CBTD16210 20-BIT FET BUS SWITCH WITH LEVEL SHIFTING

SCDS049H – MARCH 1998 – REVISED JULY 2002

- Member of Texas Instruments Widebus™ Family
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Designed to Be Used in Level-Shifting Applications

## description/ordering information

The SN74CBTD16210 provides 20 bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay. A diode to  $V_{CC}$  is integrated in the circuit to allow for level shifting from 5-V signals at the device inputs to 3.3-V signals at the device outputs.

The device is organized as a dual 10-bit bus switch with separate output-enable ( $\overline{OE}$ ) inputs. It can be used as two 10-bit bus switches or as one 20-bit bus switch. When  $\overline{OE}$  is low, the associated 10-bit bus switch is on, and port A is connected to port B. When  $\overline{OE}$  is high, the switch is open, and the high-impedance state exists between the ports.

## DGG, DGV, OR DL PACKAGE (TOP VIEW)

NC	1	48	$1\overline{OE}$
1A1	2	47	$2\overline{OE}$
1A2	3	46	1B1
1A3	4	45	1B2
1A4	5	44	1B3
1A5	6	43	1B4
1A6	7	42	1B5
GND	8	41	GND
1A7	9	40	1B6
1A8	10	39	1B7
1A9	11	38	1B8
1A10	12	37	1B9
2A1	13	36	1B10
2A2	14	35	2B1
$V_{CC}$	15	34	2B2
2A3	16	33	2B3
GND	17	32	GND
2A4	18	31	2B4
2A5	19	30	2B5
2A6	20	29	2B6
2A7	21	28	2B7
2A8	22	27	2B8
2A9	23	26	2B9
2A10	24	25	2B10

NC – No internal connection

## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SSOP – DL	Tube	SN74CBTD16210DL	CBTD16210
		Tape and reel	SN74CBTD16210DLR	
	TSSOP – DGG	Tape and reel	SN74CBTD16210DGGR	CBTD16210
	TVSOP – DGV	Tape and reel	SN74CBTD16210DGV	CYD210

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

## FUNCTION TABLE (each 10-bit bus switch)

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Z



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**SN74CBTD16210**  
**20-BIT FET BUS SWITCH**  
**WITH LEVEL SHIFTING**

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**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT	
$V_{IK}$		$V_{CC} = 4.5\text{ V}$ ,	$I_I = -18\text{ mA}$			-1.2	V	
$V_{OH}$		See Figure 2						
$I_I$		$V_{CC} = 0\text{ V}$ ,	$V_I = 5.5\text{ V}$			10	$\mu\text{A}$	
		$V_{CC} = 5.5\text{ V}$ ,	$V_I = 5.5\text{ V or GND}$			$\pm 1$		
$I_{CC}$		$V_{CC} = 5.5\text{ V}$ ,	$I_O = 0$ ,			1.5	mA	
$\Delta I_{CC}^\ddagger$	Control inputs	$V_{CC} = 5.5\text{ V}$ ,	One input at 3.4 V,			2.5	mA	
$C_i$	Control inputs	$V_I = 3\text{ V or 0}$				4.5	pF	
$C_{io(OFF)}$		$V_O = 3\text{ V or 0}$ ,	$\overline{OE} = V_{CC}$			5.5	pF	
$r_{on}^\S$		$V_{CC} = 4.5\text{ V}$	$V_I = 0$			5	7	$\Omega$
				$I_I = 64\text{ mA}$			5	
			$I_I = 30\text{ mA}$			35	50	
		$V_I = 2.4\text{ V}$ ,	$I_I = 15\text{ mA}$					

† All typical values are at  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

‡ This is the increase in supply current for each input that is at the specified TTL voltage level rather than  $V_{CC}$  or GND.

§ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

**switching characteristics over recommended operating free-air temperature range,  $C_L = 50\text{ pF}$  (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$t_{pd}^\parallel$	A or B	B or A		0.25	ns
$t_{en}$	$\overline{OE}$	A or B	1.5	9.8	ns
$t_{dis}$	$\overline{OE}$	A or B	1.5	8.9	ns

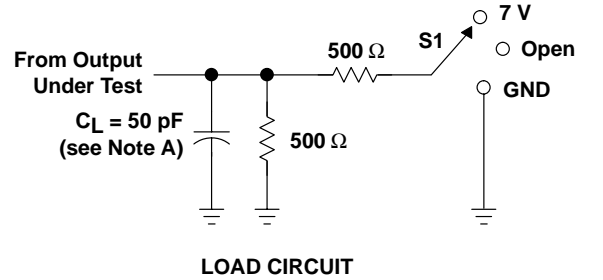
¶ The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



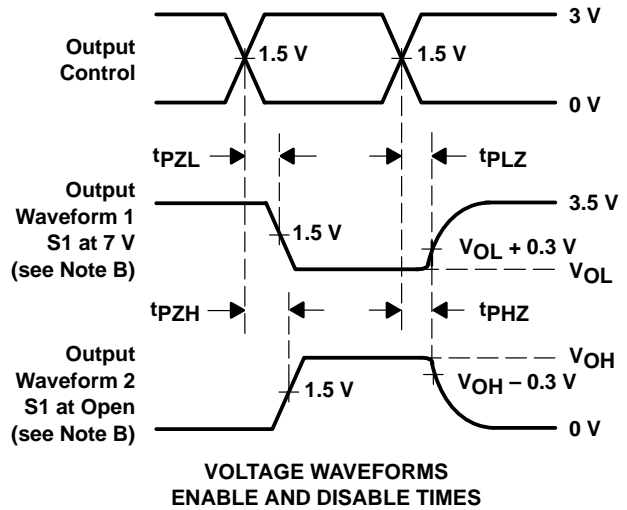
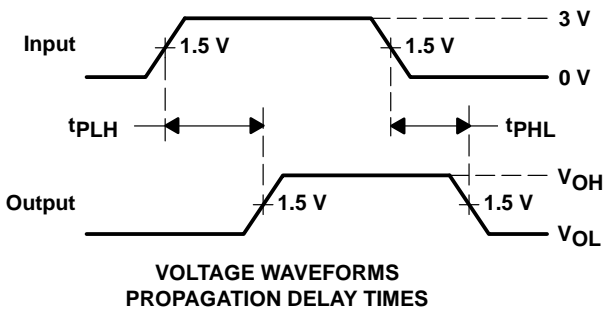
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## PARAMETER MEASUREMENT INFORMATION



TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZL}$	7 V
$t_{PHZ}/t_{PZH}$	Open



- NOTES:
- $C_L$  includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .
  - The outputs are measured one at a time with one transition per measurement.
  - $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

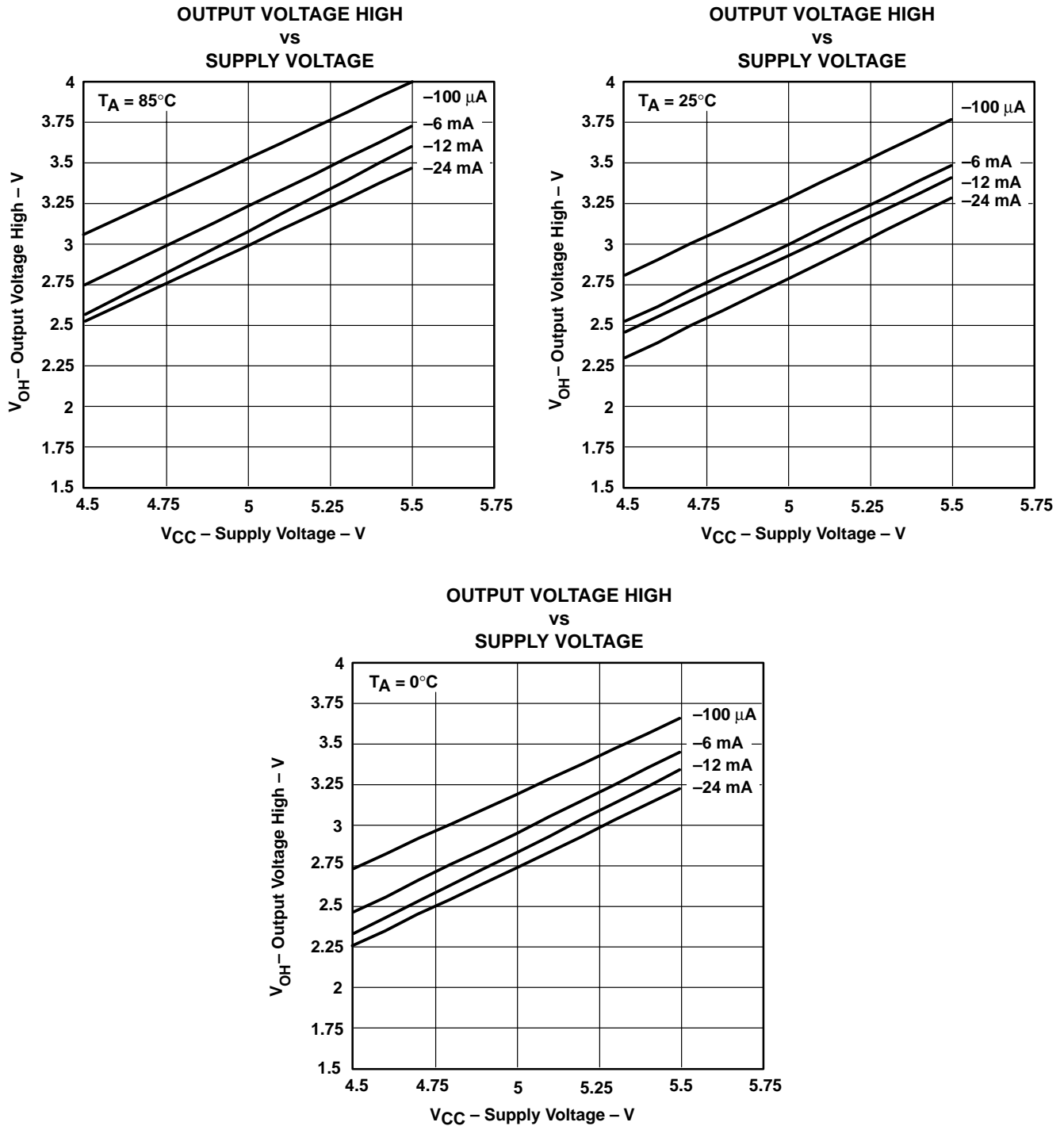


Figure 2.  $V_{OH}$  Values

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74CBTD16210DGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74CBTD16210DGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74CBTD16210DGVRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74CBTD16210DGVRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74CBTD16210DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTD16210DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTD16210DGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTD16210DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTD16210DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTD16210DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

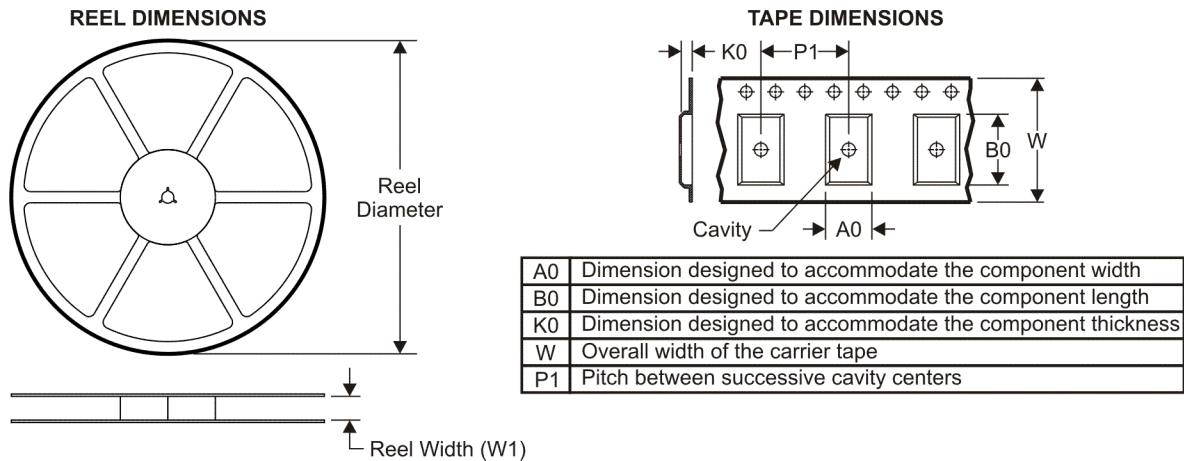
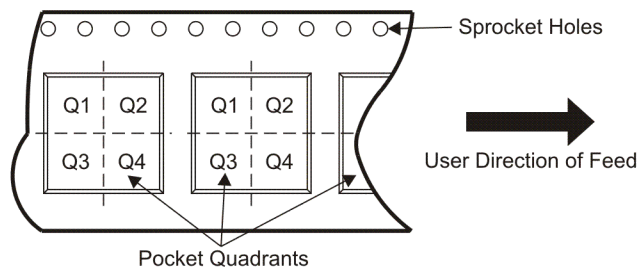
**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBTD16210DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74CBTD16210DGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74CBTD16210DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

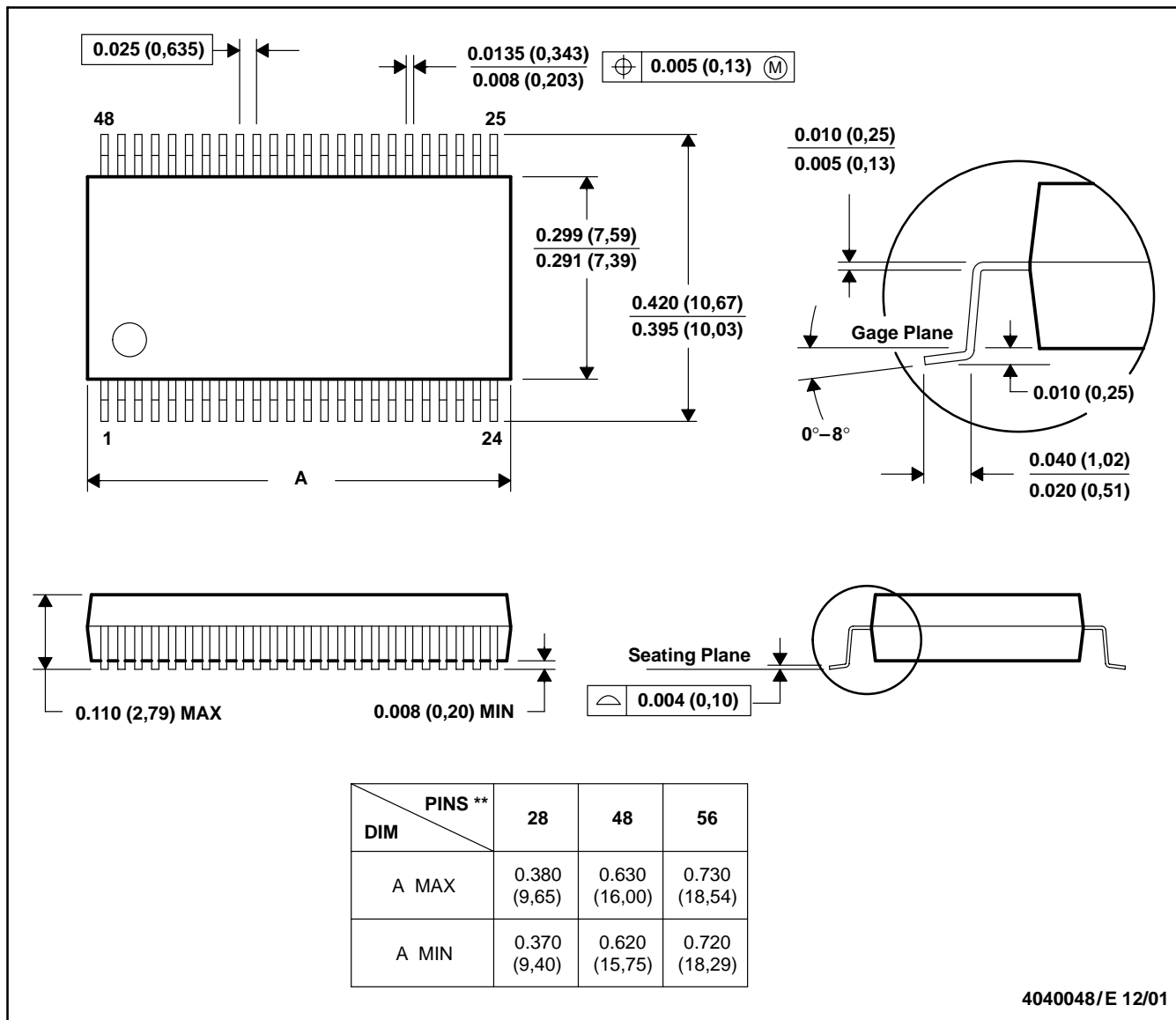
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBTD16210DGGR	TSSOP	DGG	48	2000	346.0	346.0	41.0
SN74CBTD16210DGVR	TVSOP	DGV	48	2000	346.0	346.0	33.0
SN74CBTD16210DLR	SSOP	DL	48	1000	346.0	346.0	49.0



DL (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

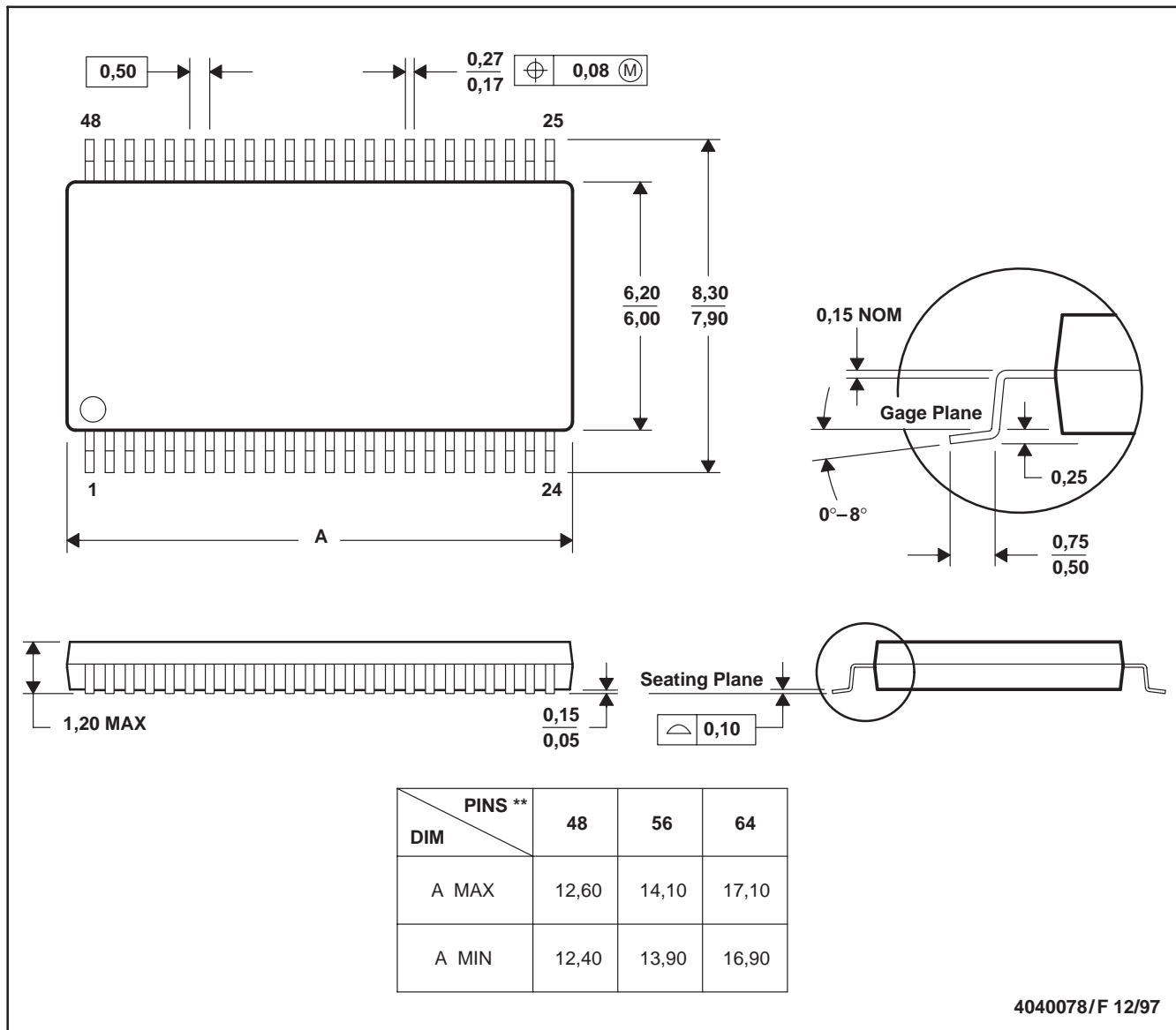


- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).  
 D. Falls within JEDEC MO-118

DGG (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

DGV (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194

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